

Product Change Notification / CENO-23PKZQ392

Date:

14-Feb-2023

Product Category:

Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6062 Initial Notice: Qualification of EN4900G as a new die attach material for KSZ8041TL, SPNY801037, KSZ8041FTLI, KSZ8041TL-TR, SPNZ801037-TR, and KSZ8041FTLI-TR catalog part numbers (CPN) available in 48L TQFP (7x7x1.0mm) package.

Affected CPNs:

CENO-23PKZQ392_Affected_CPN_02142023.pdf CENO-23PKZQ392_Affected_CPN_02142023.csv

Notification Text:

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of EN4900G as a new die attach material for KSZ8041TL, SPNY801037, KSZ8041FTLI, KSZ8041TL-TR, SPNZ801037-TR, and KSZ8041FTLI-TR catalog part numbers (CPN) available in 48L TQFP (7x7x1.0mm) package.

Pre and Post Change Summary:

		Pre Cl	nange	Post Change			
Assembly Site			iconductor s, Ltd (OSE)	Orient Semiconductor Electronics, Ltd (OSE)			
Wire Material		A	u	Au			
Die Attach Material		83	40	EN4900G			
Molding Compound Material		CEL-92	200HF	CEL-9200HF			
Lead-Frame	Material	C7025		C7025			
	Paddle Size	120x120 mils	160x160 mils	120x120 mils			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change: To improve manufacturability by qualifying EN4900G as a new Die attach material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date:May 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	January 2022					>	May 2023				
Workweek	1	2	3	4	5		1 8	1 9	2 0	2 1	2 2
Initial PCN Issue Date				х							
Qual Report Availability										х	
Final PCN Issue										Х	

Date

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: January 27, 2023: Issued initial notification.

February 14, 2023: Re-issued initial notification. Update the Pre and Post Change Summary to include Lead Frame Paddle size and attached Pre and Post Change Summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_CENO-23PKZQ392_Pre and Post Change_Summary.pdf PCN_CENO-23PKZQ392_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. CENO-23PKZQ392 - CCB 6062 Initial Notice: Qualification of EN4900G as a new die attach material for KSZ8041TL, SPNY801037, KSZ8041FTLI, KSZ8041TL-TR, SPNZ801037-TR, and KSZ8041FTLI-TR catalog part numbers (CPN) available in 48L TQFP (7x7x1.0mm) package.

Affected Catalog Part Numbers (CPN)

KSZ8041TL SPNY801037 KSZ8041FTLI KSZ8041TL-TR SPNZ801037-TR KSZ8041FTLI-TR